

In the Claims:

Please cancel claims 8-11.

Please amend claim 12 to read as follows:

8-12. (Three Times Amended) A sensor comprising:

a first chip of semiconductor material;

a sensor element having a movable microstructure, the sensor element supported by the first chip and structured to generate a first signal in response to a movement of the microstructure relative to the first chip;

a second chip of semiconductor material covering the sensor element and configured to receive the first signal, the second chip of semiconductor material comprising a processing circuit formed therein and electrically coupled to the sensor element to receive the first signal, the processing circuit structured to process the first signal and generate a second signal based on the first signal; and

a wall formed on the first chip and surrounding the sensor element and connecting the first chip to the second chip, the wall defining a hermetically sealed chamber between the first chip and the second chip and enclosing the sensor element.

REMARKS

Claims 1-7, 12, 13, and 15-20 are presented for further examination. Claims 8-11 have been cancelled and claim 12 has been amended.

In the final Office Action dated April 10, 2001, the Examiner rejected claims 1-7, 12, 13, and 15-20 under 35 U.S.C. § 103(a) as unpatentable over U.S. Patent No. 5,864,063 ("Otani et al.") in view of WO 96/396,632 ("Martin et al."). The remarks accompanying the rejection stated that Otani et al. discloses, *inter alia*, "at least one moveable microstructure 14 relative to a surface of the first chip wherein the sensing element 14 is formed on the chip" (emphasis added).

Applicants respectfully disagree with the basis for the rejection and request reconsideration and further examination of the claims.